IN THE CLAIMS

1 (Currently Amended). A device comprising:

more than one spring electrical contact to contact a first ~~surface of an object~~ side of a wafer, said first side ~~surface~~ of said wafer ~~object~~ to have a material electrodeposited thereon; and

a base to directly support said first side ~~surface~~ of said wafer ~~object~~ without being directly connected to said spring electrical contacts, said base to ~~distribute the force to~~ seal a second ~~surface of said object~~ side of said wafer, said second side opposite to said first side.

2 (Original). The device of claim 1 including a soft, acid resistant material disposed on said base.

3 (Original). The device of claim 1 wherein said base is spaced inward from said contacts.

4 (Original). The device of claim 1 wherein said spring electrical contacts are connected to a frame.

5 (Original). The device of claim 4 wherein said spring electrical contacts are resilient beams that terminate with tips.

6 (Original). The device of claim 5 wherein said object has an outer edge, said base to distribute a force at said object outer edge and said tips to contact said object inward from said base.

7 (Original). The device of claim 4 wherein said base and said frame are annular.

8 (Original). The device of claim 4 wherein said frame and said beams are coated with an acid-resistant material.

9 (Currently Amended). The device of claim 1 wherein said base substantially continuously contacts said ~~surface~~ side.

10 (Currently Amended). The device of claim 1 wherein said spring electrical contacts independently deflect while electrical contact is made with said ~~object~~ wafer.

Claims 11-30 (Canceled).